



Application Data Sheet

Application Information

Application number:: 10632553
Filing Date:: 08/02/03
Application Type:: Regular
Subject Matter:: Utility
Title:: Semiconductor multi-package module having package stacked over die-down flip chip ball grid array package and having wire ~~bond~~ bond interconnect between stacked packages
Attorney Docket Number:: CPAC 1017-6 D4
Total Drawing Sheets:: 7
Small Entity?:: No

Applicant Information

Applicant Authority Type: Inventor
Primary Citizenship Country: US
Status: Full Capacity
Given Name: Marcos
Family Name: Karnezos
City of Residence: Palo Alto
State or Province of Residence: CA
Country of Residence: US
Street of mailing address: 535 Lytton Avenue
City of mailing address: Palo Alto
State or Province of mailing address: CA
Country of mailing address: US
Postal or Zip Code of mailing address: 94301

Correspondence Information

Correspondence Customer Number:: 22470

Representative Information

Representative Customer Number::	22470	
----------------------------------	-------	--

Domestic Priority Information

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application	An application claiming the benefit under 35 USC 119 (e)	60411590	17 September 2002

Assignee Information

Assignee name:: ChipPAC, Inc.
Street of mailing address:: 47400 Kato Road
City of mailing address:: Fremont
State or Province of mailing address:: CA
Country of mailing address:: US
Postal or Zip Code of mailing address:: 94538